

II-VI Incorporated Introduces Small Form-Factor Dual Interleaver

PITTSBURGH, August 31, 2017 (GLOBE NEWSWIRE) – II-VI Incorporated (NASDAQ:IIVI), a leading provider of solutions for next generation optical networks today announced the introduction of its small form-factor dual interleaver platform for high bit rate transmission and emerging applications in optical access networks.

Next generation broadband access networks require compact equipment to fit in small spaces in the outside plant. II-VI's small 37 x 39 x 12 mm dual interleavers are uniquely designed to enable network operators to increase capacity by deploying dense wavelength division multiplexing (DWDM) technology in locations where space is at a premium such as in remote nodes or base stations.

“By building on our heritage as a pioneer in interleaver technology and by leveraging our strong core competency in micro optics, we achieved a small and cost-effective product to serve new high growth market opportunities including high bit rate transmission and wireless access,” said Dr. Sanjai Parthasarathi, Vice President, Product Marketing and Strategy, Optical Communications Group. “The very compact size and cost effectiveness was achieved by optimizing a vertically integrated design that includes optical materials, coatings, components and assemblies.”

II-VI's interleavers enable DWDM networks to increase transmission capacity efficiently by doubling the number of channels within the same wavelength range. The small form-factor dual Interleaver platform features two interleavers, one for multiplexing and another for de-multiplexing DWDM wavelengths, both in a single compact package. The product leverages II-VI's advanced Gires-Tournois etalon technology that features a wide channel passband and high adjacent channel isolation for high bit rate and cascaded architectures. Its design is optimized to complement II-VI's high performance wavelength add/drop thin-film filter technology. II-VI's small form-factor dual interleavers are available now for evaluation in sample quantities.

II-VI at ECOC 2017, Sep. 18-20, 2017, Booth #252

II-VI will showcase new products at ECOC 2017 that are driven by advances in our materials and technology platforms. The product showcase will include differentiated subsystems solutions, highly compact optical amplifier solutions tailored to enable high bit-rate DWDM transceivers, novel embedded monitoring solutions for transport networks, as well as key devices and sub-assemblies for datacenter transceivers.



About II-VI Incorporated

II-VI Incorporated, a global leader in engineered materials and opto-electronic components is a vertically integrated manufacturing company that develops innovative products for diversified applications in the industrial, optical communications, military, life sciences, semiconductor equipment, and consumer markets. Headquartered in Saxonburg, Pennsylvania, with research and development, manufacturing, sales, service, and distribution facilities worldwide, the Company produces a wide variety of application-specific photonic and electronic materials and components, and deploys them in various forms including integrated with advanced software to enable our customers. For more information, visit us at www.ii-vi.com.

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